



## Final Product Change Notification

201709019F01

**Issue Date:** 30-Mar-2018  
**Effective Date:** 28-Jun-2018

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# QUALITY

### Management Summary

Assembly transfer of the FXLS8471QR1 from Amkor Korea (ATK1) to ASE-Chungli Taiwan (ASECL) assembly site for continuous customer supply.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input checked="" type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

## FXLS8471QR1 ASECL Transfer and Copper Wire Qualification

### Details of this Change

NXP Semiconductors announces the assembly transfer of FXLS8471QR1 to ASE-Chungli Taiwan (ASECL) assembly site. These products were previously assembled at the Amkor Korea (ATK1) assembly site.

With this change, NXP Semiconductors also announces the materials change to Gold Palladium Copper (AuPdCu) wire, Sumitomo EME-G700LA version P mold compound, Ablestik Die Attach Film (DAF) ATB-125HA2 and Mitsui Rough Palladium Pre-plated Frame (PPF) with Nickel Palladium Gold (NiPdAu) C7025 material for FXLS8471QR1. These products were previously assembled with Gold (Au) wire, Sumitomo EME-G700 mold compound, Ablestik ATB-120A DAF and LGI (STW) PPF (micro NiPdAuAg) C7025 material.

### Why do we Implement this Change

The transfer to ASECL is for supply continuity as a result of ATK1 closure. The transfer from Gold to Gold Palladium Copper wire is an alignment to industry standard convention for wirebond material type. The change to mold compound and die attach material for QFN 3x3 package is required to standardize the bill of materials for ASECL assembly production.

### Identification of Affected Products

Product identification does not change

There is no change to the orderable part numbers. NXP will have traceability of the assembly site by the 1st and 2nd digit of the tracecode.

### Product Availability

#### Sample Information

Samples are available from 23-Mar-2018

## Production

Planned first shipment 23-Mar-2018

### Impact

no impact to the product's functionality anticipated.  
No impact to product form, fit, function or reliability is expected.

### Disposition of Old Products

Existing inventory will be shipped until depleted

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 29-Apr-2018.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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### Part Number Affected

FXLS8471QR1